

PCN Number:	20140408002	PCN Date:	04/15/2014
Title:	Qualification of TI Malaysia as Additional Assembly/Test Site for Select Devices		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	07/15/2014	Estimated Sample Availability:	Date Provided at Sample request

Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Qualification of TI Malaysia as Additional Assembly/Test Site for Select Devices. Material differences are as follows:

- Group 1 – Devices that will have Mold Compound change only**

	MEX	MLA
Mold Compound	4205694, 4211880	4209640

- Group 2 – No material differences**

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Mexico	Assembly Site Origin (22L)	ASO: MEX
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2d:
 MSL '2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT: 39
 ITEM: LBL: 5A (L)T0:1750
 (1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: TI-Mexico = M, TI-Taiwan = T, [TI-Malaysia = K](#)

Product Affected: Group 1			
SN1106046D	TPS5402DR	TPS5403DR	TPS5405DR
SN1106046DR			
Product Affected: Group 2			
HPA00836PWPR	TPA3020D2PWPR	TPA3111D1PWPR	TPA3113D2PWP
HPA00928PWPR	TPA3110D2PWP	TPA3112D1PWP	TPA3113D2PWPR
HPA01070PWPR	TPA3110D2PWPR	TPA3112D1PWPR	
HPA01071PWPR	TPA3110LD2PWPR	TPA3112SD1PWP	
TPA3020D2PWP	TPA3111D1PWP	TPA3112SD1PWPR	

Group 1 : Qualification Data				
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle : TPS5405D (MSL1-260C)				
Package Construction Details				
Assembly Site:	MLA	Mold Compound:	4209640	
# Pins-Designator, Family:	8-D, SOIC	Mount Compound:	4042500	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
Electrical Characterization	-	30/0	-	-
Manufacturability Qualification (MQ)		Pass	-	-
**High Temp Storage Bake	170C (420 hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/150C (500 Cycles)	77/0	77/0	77/0
Moisture Sensitivity	L1-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 1-260C.				
Group 2 : Qualification Data				
Qual Vehicle 1 : SN89062PWP (MSL2-260C)				
Package Construction Details				
Assembly Site:	MLA	Mold Compound:	4205443	
# Pins-Designator, Family:	24-PWP, HTSSOP	Mount Compound:	4208458	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.30 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**Life test	125C (1000 hrs)	77/0	-	-
**Biased HAST	130C/85%RH (96 hrs)	77/0	77/0	77/0
**Autoclave	121C, 2atm (96 hrs)	77/0	77/0	77/0
**High Temp Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/150C (500 Cycles)	77/0	77/0	77/0
**Thermal Shock	-65C/150C (500 Cycles)	77/0	77/0	77/0
Manufacturability Qualification (MQ)		Pass	-	-
Moisture Sensitivity	L2-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 2-260C.				

Qual Vehicle 2 : SN84001PWP (MSL2-260C)			
Package Construction Details			
Assembly Site:	MLA	Mold Compound:	4205443
# Pins-Designator, Family:	28-PWP, HTSSOP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size / Fail	
**Life test	125C (1000 hrs)	77/0	
**Biased Temp and Humidity	85C/85%RH (1000 hrs)	77/0	
**Autoclave	121C, 2atm (96 hrs)	77/0	
**High Temp Storage Bake	170C (420 hrs)	77/0	
**Temp Cycle	-65C/150C (500 Cycles)	77/0	
Manufacturability Qualification (MQ)		Pass	
**- Preconditioning sequence: Level 2-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com